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08863759

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CONFIRMATORY INSTRUMENT

1) Name of Contractor M/A-COM, A Division of AMP INCORPORATED (CAGE Code 96341)	2) Contract No. F33615-94-C-1408
3) Title of Inventions a. A Two-Layer Hermetic-Like Coating Process for On-Wafer Encapsulation of GaAs MMIC's, and b. A Two-Layer Hermetic-Like Coating Process for On-Wafer Encapsulation of GaAs MMIC's Having Flip-Chip Bonding Capabilities	
4) Name of Inventor(s) (Last, First, MI) Varmazis, Costas, and Kaleta, Anthony	
5) Serial No. a. US Patent App # 08/863,759 b. US Patent App # 09/019,627	6) Filing Date a. May 27, 1997 (priority from Dec 21, 1995) b. February 6, 1998 (continuation-in-part of a. above)

The invention identified above is a "Subject Invention" under Patent Rights clause Far 52.227-12 (June 1989) included in Contract No. F33615-94-C-1408 with USAF/AFMC/ASC, Wright Laboratory, Wright Patterson AFB, OH.

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Title of Contractor
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